Document Number: STCV25230A2C Preliminary Datasheet V1.0

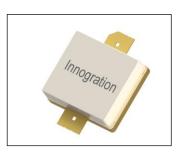
GaN 50V, 230W,2.45GHz RF Power Transistor

Description

The STCV25230A2C is a single ended 230 watt capable, GaN HEMT, ideal for ISM applications at 2.45GHz. It can be used in CW, Pulse and any other modulation modes. There is no guarantee of performance when this part is used in applications designed outside of these frequencies.

• Typical RF performance at selected 2.4-2.5GHz applications with device soldered on heatsink VDD = 50Vdc, Vgs=-3.6V CW

Freq	P1dB	P1dB	P1dB	P1dB	P3dB	P3dB	P3dB
(MHz)	(dBm)	(W)	Eff(%)	Gain(dB)	(dBm)	(W)	Eff(%)
2400	54.07	255.2	68.1	17.89	54.7	296.0	72.3
2450	53.3	213.6	69.1	18.3	54.2	264.4	74.2
2500	52.18	165.3	68.2	18.48	53.5	225.0	75.6



Applications

- 2.45GHz RF Energy
- S band power amplifier

Important Note: Proper Biasing Sequence for GaN HEMT Transistors

Turning the device ON

- 1. Set VGS to the pinch--off (VP) voltage, typically -5 V
- 2. Turn on VDS to nominal supply voltage
- 3. Increase VGS until IDS current is attained
- 4. Apply RF input power to desired level

Turning the device OFF

- 1. Turn RF power off
- 2. Reduce VGS down to VP, typically -5 V
- 3. Reduce VDS down to 0 V
- 4. Turn off VGS

Table 1. Maximum Ratings

Rating	Symbol	Value	Unit
DrainSource Voltage	V _{DSS}	+200	Vdc
GateSource Voltage	V_{GS}	-8 to +0.5	Vdc
Operating Voltage	V_{DD}	55	Vdc
Maximum gate current	Igs	34	mA
Storage Temperature Range	Tstg	-65 to +150	°C
Case Operating Temperature	T _C	+150	°C
Operating Junction Temperature	TJ	+225	°C

Table 2. Thermal Characteristics

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case by FEA	Po 10	1.2	°C /W
T _c = 85°C, at Pd=80W	Rejc	1.3	-C /VV

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Table 3. Electrical Characteristics (TA = 25℃ unless otherwise noted)

DC Characteristics (measured on wafer prior to packaging)

Characteristic	Conditions	Symbol	Min	Тур	Max	Unit
Drain-Source Breakdown Voltage	VGS=-8V; IDS=34mA	V _{DSS}		200		V
Gate Threshold Voltage	VDS =10V, ID = 34mA	$V_{GS(th)}$	-4	-	-2	V
Gate Quiescent Voltage VDS =48V, IDS=300mA, Measured in Functional Test		$V_{GS(Q)}$		3.2		V

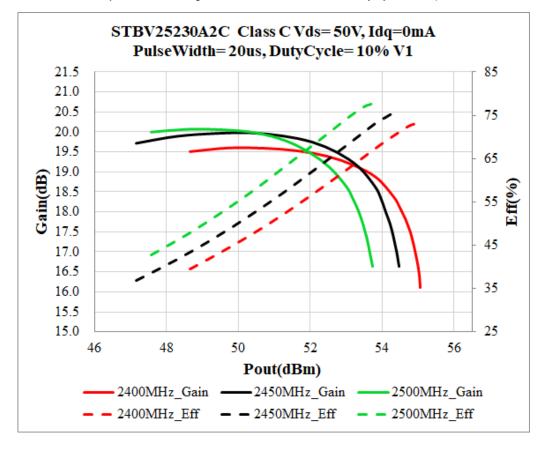
Ruggedness Characteristics

Characteristic	Conditions	Symbol	Min	Тур	Max	Unit
Load mismatch capability	2.45GHz, Pout=230W pulse CW					
	All phase,	VSWR		10:1		
	No device damages					

TYPICAL CHARACTERISTICS

Figure 1: Efficiency and power gain as function of Pout

(VDD = 50Vdc, Vgs=-4.5V, Pulse width=20us, duty cycle=10%)



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Figure 2: S11/S21 output from Network analyser

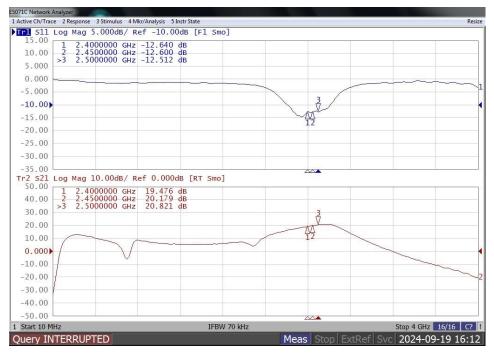
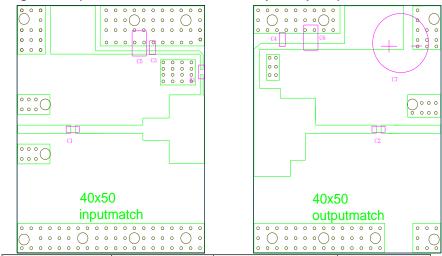


Figure 3: Reference design circuit (RO4350B 30mil, PCB DWG file upon request,)

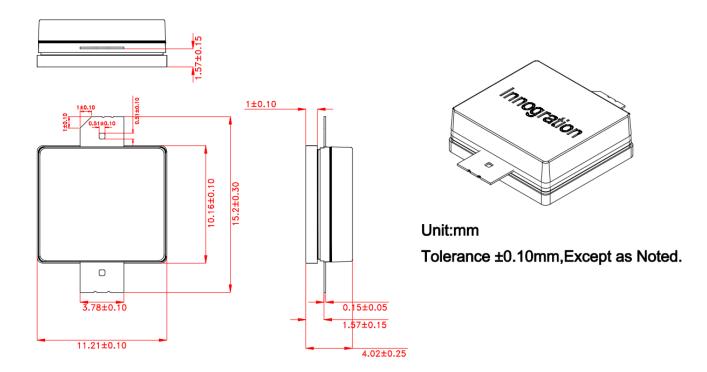


Designator	Comment	Footprint	Quantity	
C1, C2,	12 pF	0805/1210	4	
C3, C4	12 βι	(HIGH Q)	7	
OF 00	10	4040	0	
C5, C6	uF/100V	1210	2	
C7	1000		1	
C1	uF/63V		-	
R1	10 Ω	0603	1	

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Package Dimensions (Unit:mm)



Revision history

Table 1. Document revision history

Date	Revision	Datasheet Status
2024/9/19	Rev 1.0	Preliminary Datasheet

Application data based on LSM-24-29

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